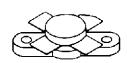


SD1726 (THA15)

RF & MICROWAVE TRANSISTORS HF SSB APPLICATIONS

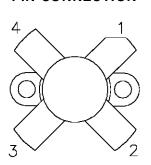
- OPTIMIZED FOR SSB
- 30 MHz
- 50 VOLTS
- IMD -30 dB
- COMMON EMITTER
- GOLD METALLIZATION
- Pout = 150 W PEP MIN. WITH 14 dB GAIN



.500 4LFL (M174) epoxy sealed

ORDER CODE SD1726 BRANDING THA15

PIN CONNECTION



- 1. Collector
- 3. Base
- 2. Emitter
- 4. Emitter

DESCRIPTION

The SD1726 is a 50 V epitaxial silicon NPN planar transistor designed primarily for SSB communications. This device utilizes emitter ballasting to achieve extreme ruggedness under severe operating conditions.

ABSOLUTE MAXIMUM RATINGS $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit	
V _{CBO}	Collector-Base Voltage	110	V	
V _{CEO}	Collector-Emitter Voltage	55	V	
V _{EBO}	Emitter-Base Voltage	4.0	V	
Ic	Device Current	10	А	
Poiss	Power Dissipation	233	W	
TJ	Junction Temperature +200		°C	
T _{STG}	Storage Temperature	- 65 to +150	°C	

THERMAL DATA

R _{TH(j-c)} Junction-Case Thermal Resistant	ce 0.75	°C/W
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November 1992 1/7

SD1726 (THA15)

ELECTRICAL SPECIFICATIONS (Tcase = 25°C)

STATIC

Symbol	Test Conditions	Value			Unit		
		Min.	Тур.	Max.			
ВУсво	I _C = 100mA	$I_E = 0mA$		110	_	_	V
BVces	I _C = 100mA	$V_{BE} = 0V$		110	_		V
BV _{CEO}	I _C = 100mA	$I_B = 0mA$		55	_	_	V
BV _{EBO}	I _E = 10mA	$I_C = 0mA$		4.0	_		V
ICEO	V _{CE} = 30V	I _E = 0mA		_	_	5	mA
Ices	V _{CE} = 60V	$I_E = 0mA$		_	_	5	mA
h _{FE}	V _{CE} = 6V	I _C = 1.4A		18	_	43.5	_

DYNAMIC

Symbol	Test Conditions			Value			Unit
Syllibol				Min.	Тур.	Max.	Oiiit
Роит	f = 30 MHz	$V_{CE} = 50 V$	$I_{CQ} = 100 \text{mA}$	150	_	_	W
G _P *	P _{OUT} = 150 WPEP	$V_{CE} = 50 \text{ V}$	$I_{CQ} = 100 \text{mA}$	14	_	_	dB
IMD*	P _{OUT} = 150 WPEP	V _{CE} = 50 V	$I_{CQ} = 100 \text{mA}$	_	_	-30	dBc
η _C *	Pout = 150 WPEP	$V_{CE} = 50 V$	$I_{CQ} = 100 \text{mA}$	37	_	_	%
Сов	f = 1 MHz	$V_{CB} = 50 V$		_	_	220	pF

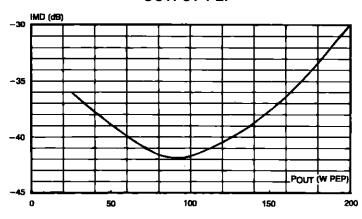
Note: The SD1726 is also usable in Class A at 40 V. Typical performance is:

 $P_{OUT} = 30 \text{ W PEP}, G_P = 14 \text{ dB}, IMD = -40 \text{dBc}$

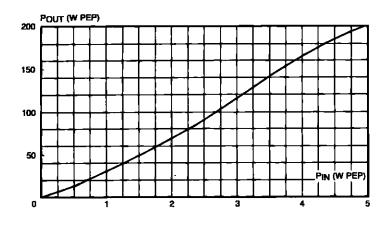
* $f_1 = 30.00 \text{ MHz}; f_2 = 30.001 \text{ MHz}$

TYPICAL PERFORMANCE

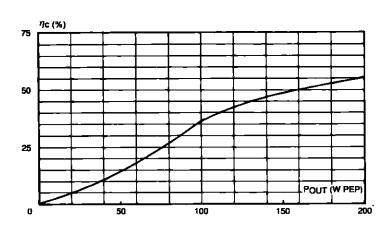




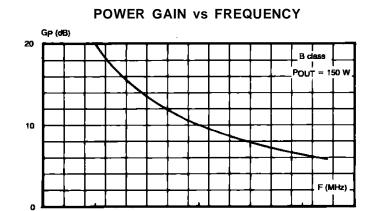
POWER OUTPUT PEP vs POWER INPUT



COLLECTOR EFFICIENCY vs POWER OUTPUT PEP



TYPICAL PERFORMANCE (cont'd)



POWER GAIN vs POWER OUTPUT PEP

75

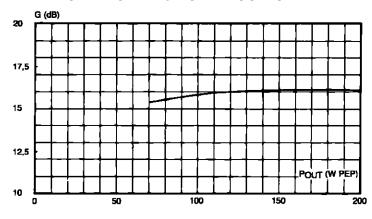
100

125

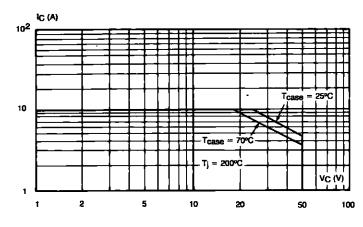
150

25

50

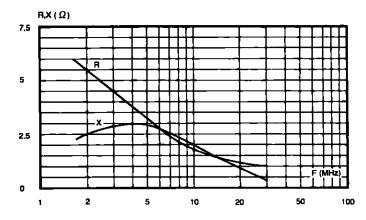


SAFE OPERATING AREA

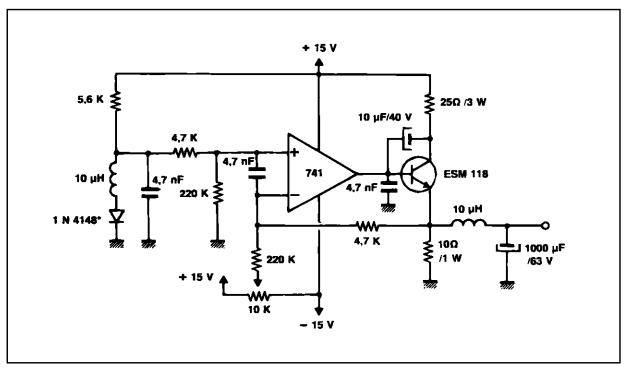


IMPEDANCE DATA

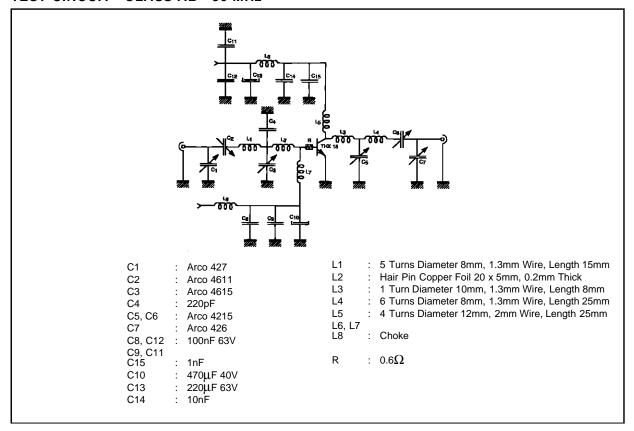
TYPICAL INPUT IMPEDANCE



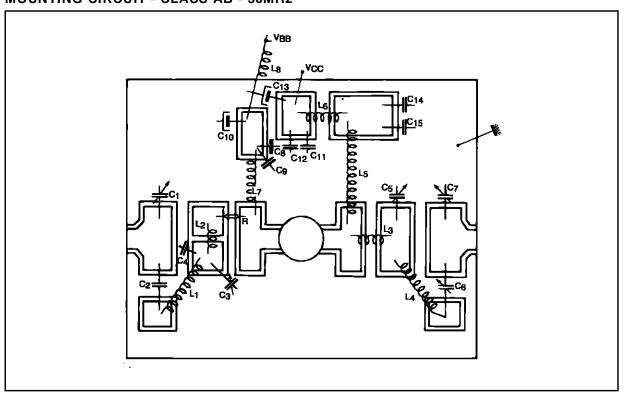
BIAS CRCUIT



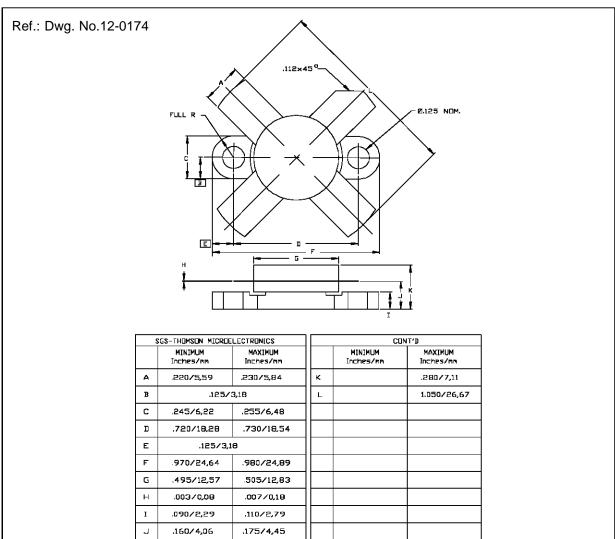
TEST CIRCUIT - CLASS AB - 30 MHz



MOUNTING CIRCUIT - CLASS AB - 30MHz



PACKAGE MECHANICAL DATA



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